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Intel® Xeon® Processor E3-1241 v3 (8M Cache, 3.50 GHz)

Specifications Essentials Performance Memory Specifications **Graphics Specifications Expansion Options** Package Specifications Advanced Technologies Intel® Data Protection Technology Intel® Platform Protection Technology

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Specifications - Essentials PCN/MDDS Information

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SR1R4 932026: PCN | MDDS 934913: PCN | MDDS

Lauren Date	Canalin		1
Processor Number E3-1241V3	Status		Launched
Intel® Smart Cache DM12	Launch Date		Q2'14
DMI2	Processor Number		E3-1241V3
# of OPI Links	Intel® Smart Cache		8 MB
Instruction Set S4-bit Instruction Set Extensions S5E 4.1/4.2, AVX 2.0 Embedded Options Available Q	DMI2		5 GT/s
Instruction Set Extensions	# of QPI Links		0
Embedded Options Available Lithography 22 nm Scalability Thermal Solution Specification Recommended Customer Price BOX: \$273.00 TRAY: \$262.00 Datasheet Link Performance # of Cores # of Cores # of Threads Box factors # of Mark Turbo Frequency Box factors # of Memory Specifications # of Memory Specificati	Instruction Set		64-bit
Embedded Options Available Lithography 22 nm Scalability Thermal Solution Specification Recommended Customer Price BOX: \$273.00 TRAY: \$262.00 Datasheet Link Performance # of Cores # of Cores # of Threads Box factors # of Mark Turbo Frequency Box factors # of Memory Specifications # of Memory Specificati	Instruction Set Extensions		SSE 4.1/4.2. AVX 2.0
Lithography 22 mm Scalability 15 Only Thermal Solution Specification Price BOX \$273.00 Recommended Customer Price BOX \$273.00 TRAY: \$262.00 Datasheet Link Performance # of Cores 4 # of Threads 9 Processor Base Frequency 3.5 GHz Max Turbo Frequency 3.9 GHz TDP 80 W Memory Specifications Max Memory Size (dependent on memory type) 32 GB Memory Types DR3-1333/1600 # of Memory Channels 2 # of Memory Specifications Processor Graphics 4 # of Graphics Specifications Processor Graphics 4 # of Processor Graphics 4 # None Processor Graphics 4 # None Processor Graphics 5 # Package Specifications Processor Graphics 4 # None Processor Graphics 5 # None Processor Graphics 4 # None Processor Graphics 5 # None Processor Graphics 4 # None Processor Graphics 4 # Processor Graphi		0	
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Thermal Solution Specification PCG 20130 Recommended Customer Price BOX: \$273.00 TRAY: \$262.00 Datasheet Link Performance # of Cores 4 # of Threads 8 Processor Base Frequency 3.5 GHz Max Turbo Frequency 3.9 GHz TDP 80 W Memory Specifications Max Memory Size (dependent on memory type) 32 GB Memory Types DDR3-1333/1600 # of Memory Specifications Max Memory Specifications Max Memory Specifications Max Memory Specifications Max Memory Specifications Processor Graphics 4 CCC Memory Supported 1 CG Graphics Specifications Processor Graphics 4 None Fexpension Options PCI Express Revision 3.0 PCI Express Configurations 1 Max W of PCI Express Lanes 16 Package Specifications Max CPU Configuration 1 Package Specifications Max CPU Configuration 1 Package Size 37 Smm x 37 Smm Graphics and IMC Lithography 22nm Sockets Supported FCLGA1150 Low Halogen Options Available See MDDS Advanced Technology 4 Intel® Turbo Boost Technology 4 Intel® Virtualization Technology 4 Intel® Virtualization Technology 4 Intel® Virtualization Technology 5 Q Yes Intel® Tixakin Extended Page Tables (EPT) 1 Intel® Virtualization Technology 5 Q Yes Intel® Task Memory Access Yes Intel® Task Memory Access Yes Intel® Fast Memory Access Yes Intel® State Image Platform Program (SIPP) Yes Intel® State Image Platform Program (SIPP)			
Recommended Customer Price TEAM: \$262.00 Datasheet Link Performance # of Cores	Scalability		
RECOMMendade Lustomer Price Datasheet Link Performance # of Cores # of Threads # of Well And Frequency # of Well And Frequency # of Memory Specifications Max Memory Specifications Max Memory Specifications # of Memory Channels # of Memory Channels # of Memory Specifications # of Processor Graphics # None Expansion Options # Of Pot Express Revision # of Pot Express Configurations # 1	Thermal Solution Specification		PCG 2013D
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# of Threads	- Performance		
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Max Turbo Frequency 3.9 GHz TDP 80 W Memory Specifications	# of Threads		8
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Intel® Stable Image Platform Program (SIPP) - Intel® Data Protection Technology AES New Instructions Secure Key Yes	■ Package Specifications Max CPU Configuration Package Size Graphics and IMC Lithography Sockets Supported Low Halogen Options Available ■ Advanced Technologies Intel® Turbo Boost Technology ‡ Intel® VPro Technology ‡ Intel® Hyper-Threading Technology † Intel® Virtualization Technology (VT-x) ‡ Intel® Virtualization Technology for Directed I/O (VT-d) ‡ Intel® TSX-NI Intel® TSX-NI Intel® 64 ‡ Idle States Enhanced Intel SpeedStep® Technology Thermal Monitoring Technologies Intel® Fast Memory Access	Q Q Q	1 37.5mm x 37.5mm 22nm FCLGA1150 See MDDS 2.0 Yes
Intel® Data Protection Technology AES New Instructions Secure Key Yes	■ Package Specifications Max CPU Configuration Package Size Graphics and IMC Lithography Sockets Supported Low Halogen Options Available ■ Advanced Technologies Intel® Turbo Boost Technology ‡ Intel® VPro Technology ‡ Intel® Hyper-Threading Technology † Intel® Virtualization Technology (VT-x) ‡ Intel® Virtualization Technology for Directed I/O (VT-d) ‡ Intel® VT-x with Extended Page Tables (EPT) ‡ Intel® TSX-NI Intel® G4 ‡ Idle States Enhanced Intel SpeedStep® Technology Thermal Monitoring Technologies Intel® Fast Memory Access Intel® Flex Memory Access	Q Q Q	1 37.5mm x 37.5mm 22nm FCLGA1150 See MDDS 2.0 Yes
AES New Instructions Secure Key Yes	- Package Specifications Max CPU Configuration Package Size Graphics and IMC Lithography Sockets Supported Low Halogen Options Available - Advanced Technologies Intel® Turbo Boost Technology ‡ Intel® VPro Technology ‡ Intel® Hyper-Threading Technology (VT-x) ‡ Intel® Virtualization Technology (VT-x) ‡ Intel® Virtualization Technology for Directed I/O (VT-d) ‡ Intel® VT-x with Extended Page Tables (EPT) ‡ Intel® TSX-NI Intel® 64 ‡ Idle States Enhanced Intel SpeedStep® Technology Thermal Monitoring Technologies Intel® Fast Memory Access Intel® Flex Memory Access Intel® Identity Protection Technology ‡	Q Q Q	1 37.5mm x 37.5mm 22nm FCLGA1150 See MDDS 2.0 Yes
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	- Package Specifications Max CPU Configuration Package Size Graphics and IMC Lithography Sockets Supported Low Halogen Options Available - Advanced Technologies Intel® Turbo Boost Technology ‡ Intel® VPro Technology ‡ Intel® Virtualization Technology (VT-x) ‡ Intel® Virtualization Technology for Directed I/C (VT-d) ‡ Intel® VT-x with Extended Page Tables (EPT) ‡ Intel® TSX-NI Intel® 64 ‡ Idle States Enhanced Intel SpeedStep® Technology Thermal Monitoring Technologies Intel® Fast Memory Access Intel® Flex Memory Access Intel® Identity Protection Technology † Intel® Stable Image Platform Program (SIPP) - Intel® Data Protection Technology	Q Q Q	1 37.5mm x 37.5mm 22nm FCLGA1150 See MDDS 2.0 Yes
Intol® Distferes Dustactica Tacknelland	■ Package Specifications Max CPU Configuration Package Size Graphics and IMC Lithography Sockets Supported Low Halogen Options Available ■ Advanced Technologies Intel® Turbo Boost Technology ‡ Intel® VPro Technology ‡ Intel® Virtualization Technology (VT-x) ‡ Intel® Virtualization Technology for Directed I/C (VT-d) ‡ Intel® VT-x with Extended Page Tables (EPT) ‡ Intel® TSX-NI Intel® 64 ‡ Idle States Enhanced Intel SpeedStep® Technology Thermal Monitoring Technologies Intel® Fast Memory Access Intel® Flex Memory Access Intel® Identity Protection Technology ‡ Intel® Stable Image Platform Program (SIPP) ■ Intel® Data Protection Technology	Q Q Q	1 37.5mm x 37.5mm 22nm FCLGA1150 See MDDS 2.0 Yes
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